

infrared furnace

SMD-206

Table-top Infrared Solder Reflow System for the attachment of Surface Mounted Devices



Ideal for smaller SMD solder reflow requirements

The SMD-206 is a table-top size conveyorized infrared system which is perfect for the reflow solder attachment of Surface Mounted Devices on ceramic and glass epoxy substrates. It is also well suited to a variety of other curing, heating, reflow, and drying applications. Clean, efficient infrared heat is used. Heat is uniform throughout the length and width of the chamber. The unit is extremely small and compact and can be easily moved about as necessary. It operates on a standard 120V power source; just plug it in and it's ready to go.



Dense SMD assemblies such as this one with a 68 and 18 pin components on a .060" board can be processed in this remarkably small unit with ease.

RTC radiant technology corporation

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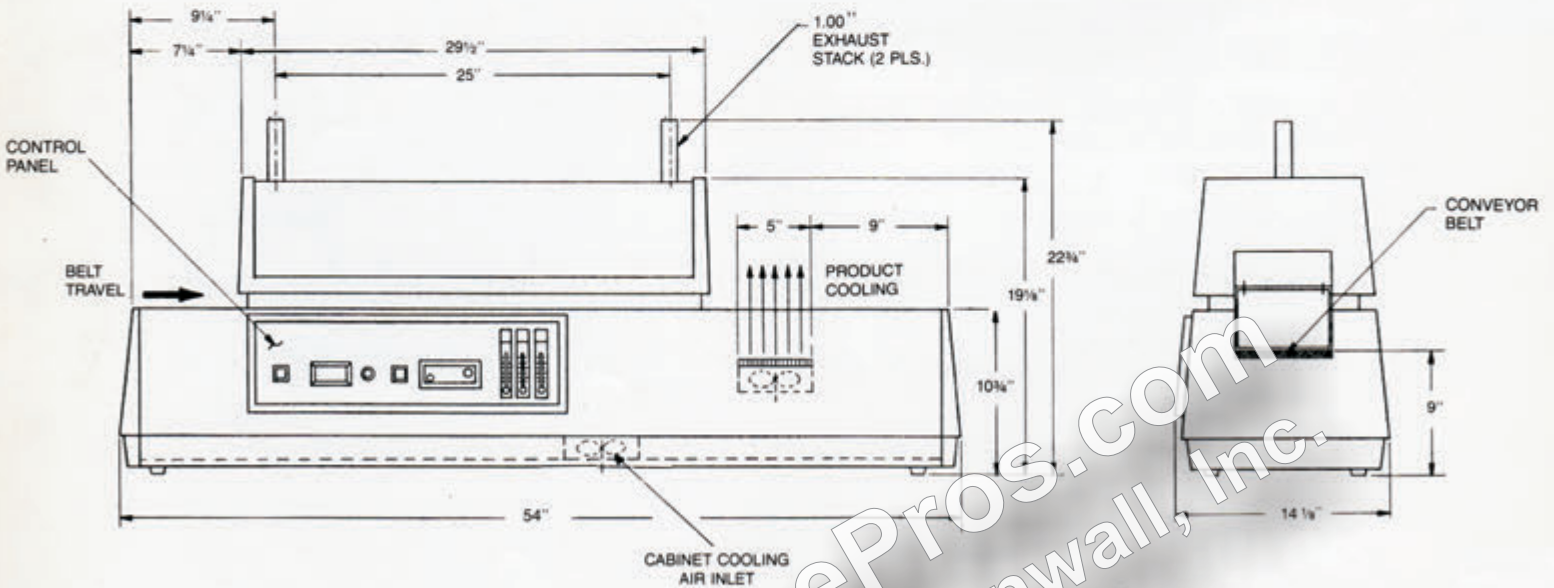
SMD-206-PCL

SPECIFICATIONS

Electrical	120V, 60hz., single-phase, 3.5kw (30 amps).
Heat	Heater lamps emit middle infrared wavelengths for temperatures to 400°C. Heat is controlled by solid state proportional digital temperature controller and Type J thermocouple in the process chamber. Phase angle fired SCR's.
Conveyor Belt	6" wide open wire Stainless Steel close weave balanced spiral. Speed is continuously variable from 0 to 60 inches per minute by a solid state digital speed control.
Weight	135 lbs. (61 kg.) Crated for shipment 200 lbs. (90.7 kg)
Atmosphere	300 scfh maximum. Air or nitrogen ¼" tubing inlet.
Exhaust	Process—Venturi assisted exhaust provides 250 scfh Cabinet—75 cfm

APPLICATIONS

- Reflow solder for the attachment of Surface Mounted Device on ceramic or glass epoxy substrates.
- Dry solder paste prior to vapor phase solder reflow.
- Cure polymer thick film materials.
- Cure bonding epoxies for attachment of components prior to wave soldering.
- Bake photo resist on silicon wafers.
- Cure epoxy potting compounds.
- Cure nomenclature and legend inks.
- Cure conformal coatings.
- Cure bonding epoxies or encapsulating epoxies on integrated circuits.
- Process heat shrink tubing.
- Dry thick film paste (to remove solvent fumes) on hybrid circuits prior to firing.



RTC also offers a complete line of production furnace systems for SMD solder reflow, hybrid thick film firing, semiconductor packaging, photovoltaic solar cell drying, firing, and annealing.

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